

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	11	("20040043570"   "20040153612"   "20050091456"   "20050108483"   "4752505"   "4845043"   "5620559"   "5805879"   "6024045"   "6336463"   "6350322"   "6492283"   "6647301"   "6690040"   "6735666").PN.	USPAT	OR	ON	2008/01/05 16:40
S2	322	"hydrogen termination"	USPAT	OR	ON	2007/03/29 12:31
S3	218	"hydrogen termination" and nitrogen	USPAT	OR	ON	2007/09/05 10:45
S4	48	"hydrogen termination" and nitrogen with temperature	USPAT	OR	ON	2007/03/29 12:32
S5	30	("2394930"   "3895127"   "4056642"   "4292343"   "4343830"   "4436761"   "4544571"   "4645683"   "4766006"   "5135775"   "5281546"   "5576071"   "5587205"   "5780115"   "5939763"   "5950107"   "5990013"   "5993916"   "6090217"   "6107192"   "6200866"   "6296715"   "6297539"   "6503330"   "6551399"   "6649543"   "6727148"   "6744104"   "6800830").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 15:22
S6	28	"6613695"	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 16:59
S10	23	"6613695"	USPAT	OR	ON	2007/03/29 18:53

S11	12	09/944734	US-PGPUB; USPAT	OR	ON	2007/03/30 11:46
S12	23	("2394930"   "3895127"   "4056642"   "4292343"   "4343830"   "4436761"   "4544571"   "4645683"   "4766006"   "5135775"   "5281546"   "5576071"   "5587205"   "5780115"   "5939763"   "5950107"   "5990013"   "5993916"   "6090217"   "6107192"   "6200866"   "6296715").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 19:46
S13	12	"6350322"	USPAT	OR	ON	2007/03/30 11:33
S14	4	"hydrogen termination" and preheat	USPAT	OR	ON	2007/09/05 10:45
S15	9	"hydrogen termination" and preheat\$3	USPAT	OR	ON	2007/09/05 10:45
S16	1	10/675575	US-PGPUB; USPAT	OR	ON	2007/09/12 14:23
S17	30567	"134".clas.	USPAT	OR	ON	2008/01/05 16:40
S18	10654	(substrate circuit wafer surface) with (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:45
S20	7035	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:46

S21	29	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3") with "800"	USPAT	OR	ON	2008/01/05 16:46
S22	437	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen adj fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:47
S23	16	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen adj fluoride or "NH.sub.3") with ("500" "600" "700" "800")	USPAT	OR	ON	2008/01/05 16:48
S24	20	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NF3 or nitrogen adj fluoride or "NF.sub.3") with ("500" "600" "700" "800")	USPAT	OR	ON	2008/01/05 16:48
S25	630	hydrogen adj termination	US-PGPUB; USPAT	OR	ON	2008/06/11 14:58
S26	82	hydrogen adj termination and ("NF. sub.3" or nitrogen adj fluoride)	US-PGPUB; USPAT	OR	ON	2008/06/11 14:59
S27	24	hydrogen adj termination and ("NF. sub.3" or nitrogen adj fluoride) same pressure	US-PGPUB; USPAT	OR	ON	2008/06/11 14:59
S28	2	"7415666"	USPAT	OR	ON	2008/09/02 17:23

S29	1	"6960975"	USPAT	OR	ON	2008/09/03 11:13
S30	397	("NF.sub.3" or nitrogen adj fluoride) with torr	US-PGPUB; USPAT	OR	ON	2008/09/03 11:17
S31	307	("NF.sub.3" or nitrogen adj fluoride) same (surface contaminants) same (torr)	US-PGPUB; USPAT	OR	ON	2008/09/03 11:21
S32	307	("NF.sub.3" or nitrogen adj fluoride) same (surface contaminants) same (torr)	US-PGPUB; USPAT	OR	ON	2008/09/03 11:21

9/ 3/ 2008 5:14:35 PM

C:\ Documents and Settings\jheckert\ My Documents\ EAST\ Workspaces\ 10-675575.wsp